INTEGRATED CIRCUITS

DATA SHEET

74LVC821A

10-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

Product specification





10-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC821A

FEATURES

- 5-volt tolerant inputs/outputs, for interfacing with 5-volt logic
- Supply voltage range of 2.7V to 3.6V
- Complies with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 10-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Flow-through pin-out architecture

DESCRIPTION

The 74LVC821A is a high performance, low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-state operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC821A is a10-bit D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-State outputs for bus-oriented applications. A clock (CP) and an output enable (OE) input are common to all flip-flops. The ten flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition. When $\overline{\text{OE}}$ is LOW, the contents of the ten flip-flops is available at the outputs.

When \overline{OE} is HIGH, the outputs go to the high impedance OFF-state. Operation of the \overline{OE} input does not affect the state of the flip-flops.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay CP to Q _n	C _L = 50 pF; V _{CC} = 3.3 V	5.4	ns
f _{max}	Maximum clock frequency	V _{CC} = 3.3 V	150	MHz
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	26	pF

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;

 $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

2. The condition is $V_I = GND$ to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDERING CODE	PKG. DWG. #
24-Pin Plastic SO	-40°C to +85°C	74LVC821A D	SOT137-1
24-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC821A DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC821A PW	SOT355-1

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PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION				
1	ŌĒ	Output enable input (active LOW)				
2, 3, 4, 5, 6, 7, 8, 9, 10, 11	D ₀ to D ₉	Data inputs				
23, 22, 21, 20, 19, 18, 17, 16, 15, 14	Q ₀ to Q ₉	3-State flip-flop outputs				
12	GND	Ground (0 V)				
13	СР	Clock input (LOW-to-HIGH, edge-triggered)				
24	V _{CC}	Positive supply voltage				

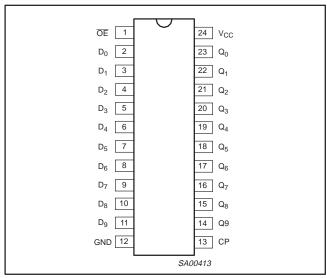
FUNCTION TABLE

OPERATING MODES		INPUTS		INTERNAL FLIP-FLOPS	OUTPUTS
OPERATING MODES	ŌĒ	СР	D _n	INTERNAL FLIP-FLOPS	Q ₀ to Q ₉
Load and read register	L L	↑	l h	L H	L H
Load register and disable outputs	H H	↑	l h	L H	Z Z
Hold	L	H or L	Х	NC	NC

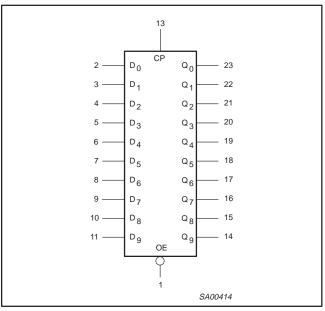
- H = HIGH voltage level
- h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition
- L = LOW voltage level
- = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition
- Z = high impedance OFF-state
- ↑ = LOW-to-HIGH clock transition

NC= no change

PIN CONFIGURATION



LOGIC SYMBOL

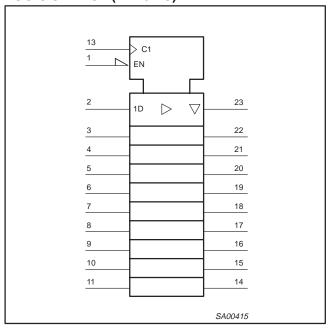


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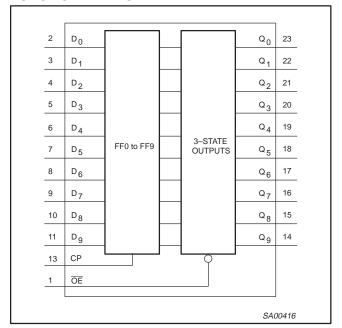
10-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

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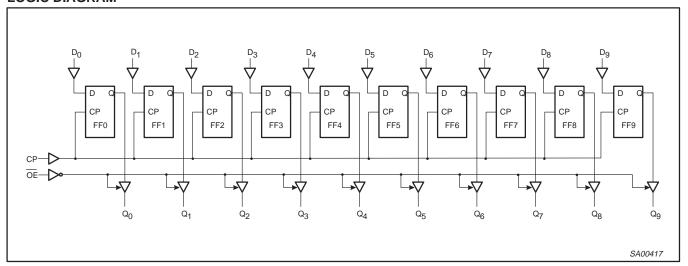
LOGIC SYMBOL (IEEE/IEC)



FUNCTIONAL DIAGRAM



LOGIC DIAGRAM



10-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	IITS	UNIT
STWIBUL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage (for max. speed performance)		2.7	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC Input voltage range		0	5.5	V
Vo	DC output voltage range; output HIGH or LOW state		0	V _{CC}	V
	DC output voltage range; output 3-State		0	5.5	
T _{amb}	Operating ambient temperature range in free-air		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7 \text{V}$ $V_{CC} = 2.7 \text{ to } 3.6 \text{V}$	0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	V
I _{IK}	DC input diode current	V _I < 0	-50	mA
VI	DC input voltage	Note 2	-0.5 to +6.5	V
I _{OK}	DC output diode current	$V_{O} > V_{CC}$ or $V_{O} < 0$	±50	mA
\/	DC output voltage; output HIGH or LOW state	Note 2	-0.5 to V _{CC} +0.5	V
Vo	DC output voltage; output 3-State	Note 2	-0.5 to 6.5	V
IO	DC output source or sink current	$V_O = 0$ to V_{CC}	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

NOTES:

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^{1.} Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

SYMBOL PARAMETER			L	IMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	+85°C	UNIT	
			MIN	TYP ¹	MAX]
.,	LUCL Love I have tweltere	V _{CC} = 1.2V	V _{CC}			V
V _{IH}	HIGH level Input voltage	V _{CC} = 2.7 to 3.6V	2.0]
V	LOW level leave to the tra	V _{CC} = 1.2V			GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V			0.8	1 °
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -12$ mA	V _{CC} -0.5			
.,	LUCLI laval autout valtage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu A$	V _{CC} -0.2	V _{CC}		
V _{OH}	HIGH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -18$ mA	V _{CC} -0.6			1 °
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -24$ mA	V _{CC} -0.8			1
		$V_{CC} = 2.7V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 12$ mA				
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu A$			0.20	V
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 24$ mA			0.55	1
I _I	Input leakage current	V _{CC} = 3.6V; V _I = 5.5V or GND		±0.1	±5	μΑ
I _{OZ}	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; $V_O = 5.5V$ or GND		0.1	±5	μА
I _{off}	Power off leakage supply	$V_{CC} = 0.0V; V_{I} \text{ or } V_{O} = 5.5V$		0.1	±10	μА
I _{CC}	Quiescent supply current	$V_{CC} = 3.6V$; $V_I = V_{CC}$ or GND; $I_O = 0$		0.1	10	μА
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7V \text{ to } 3.6V; V_I = V_{CC} - 0.6V; I_O = 0$		5	500	μΑ

All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
 The specified overdrive current at the data input forces the data input to the opposite logic input state.

AC CHARACTERISTICS

GND = 0V; t_r = $t_f \leq$ 2.5ns; C_L = 50pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C.

					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	Vco	$_{\text{C}}$ = 3.3V \pm 0	.3V	V _{CC} =	UNIT	
			MIN	TYP ¹	MAX	MIN	MAX	
t _{PHL} t _{PLH}	Propagation delay CP to Q _n	Figures 1, 4	1.5	5.4	7.3	1.5	8.5	ns
t _{PZH} t _{PZL}	3-State output enable time OE to Q _n	Figures 2, 4	1.5	5.5	7.6	1.5	8.8	ns
t _{PHZ} t _{PLZ}	3-State output disable time OE to Q _n	Figures 2, 4	1.5	3.8	6.2	1.5	6.8	ns
t _W	Clock pulse width HIGH or LOW	Figure 1	3.3	1.7	_	3.3	_	ns
t _{SU}	Setup time D _n to CP	Figure 3	1.9	0.6	_	0.9	_	ns
t _h	Hold time D _n to CP	Figure 3	1.5	0	_	1.5	_	ns
f _{max}	Maximum clock pulse frequency	Figure 1	150	200	_	150	_	MHz

1. Unless otherwise stated, all typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

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AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge$ 2.7V; V_M = 0.5 V_{CC} at $V_{CC} <$ 2.7V. V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

 V_X = V_{OL} + 0.3V at V_{CC} \geq 2.7V; V_X = V_{OL} + 0.1 V_{CC} at V_{CC} < 2.7V V_Y = V_{OH} –0.3V at V_{CC} \geq 2.7V; V_Y = V_{OH} – 0.1 V_{CC} at V_{CC} < 2.7V

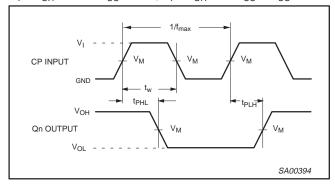


Figure 1. Clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency.

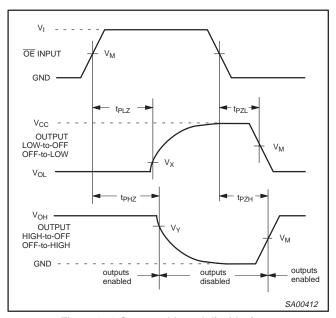


Figure 2. 3-State enable and disable times.

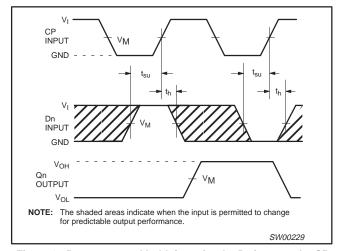


Figure 3. Data setup and hold times for the $\mathbf{D}_{\mathbf{n}}$ input to the CP input.

TEST CIRCUIT

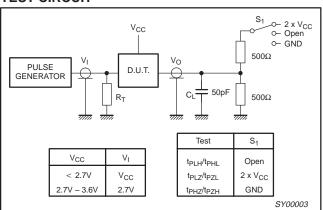


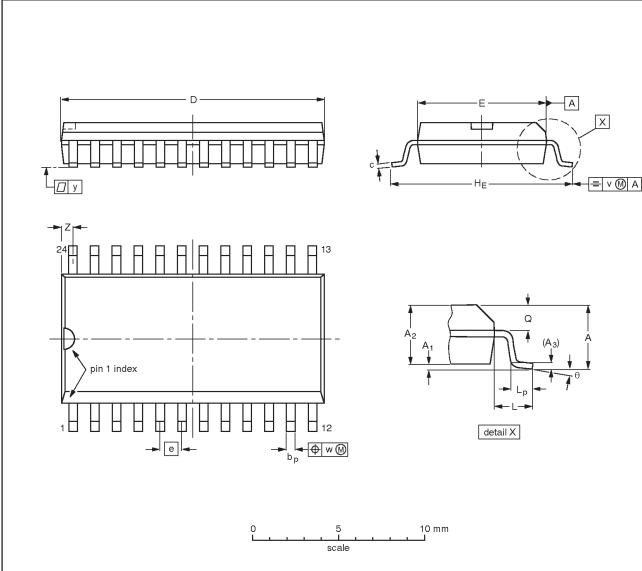
Figure 4. Load circuitry for switching times.

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SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

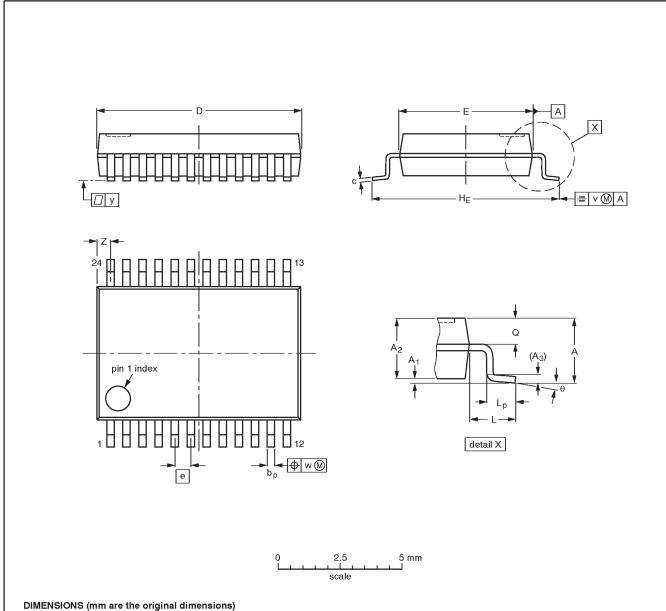
OUTLINE		REFER	RENCES		EUROPEAN	ISSUE DATE	
VERSION	IEC	IEC JEDEC EIAJ				ISSUE DATE	
SOT137-1	075E05	MS-013AD				-95-01-24 97-05-22	

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SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



UNIT	A max.	Α1	A ₂	A ₃	bр	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Œ	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

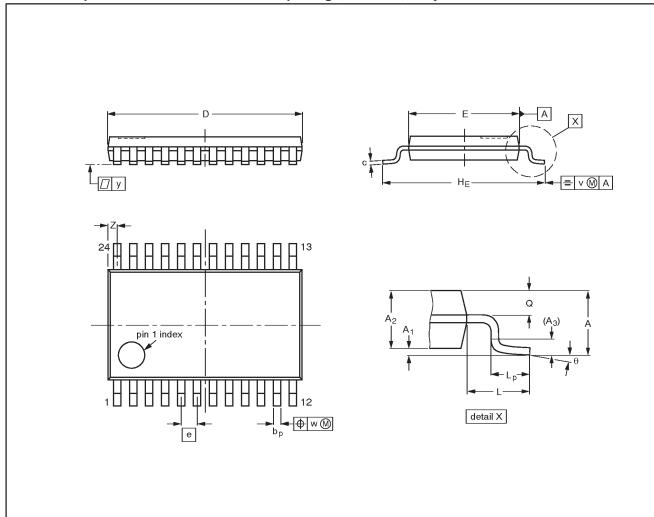
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VERSION	SION IEC JEDEC E		EIAJ		ISSUE DATE	
SOT340-1		MO-150AG				-93-09-08 95-02-04

10-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

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TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	А3	bр	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT355-1		MO-153AD			93-06-16 95-02-04

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NOTES

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Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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